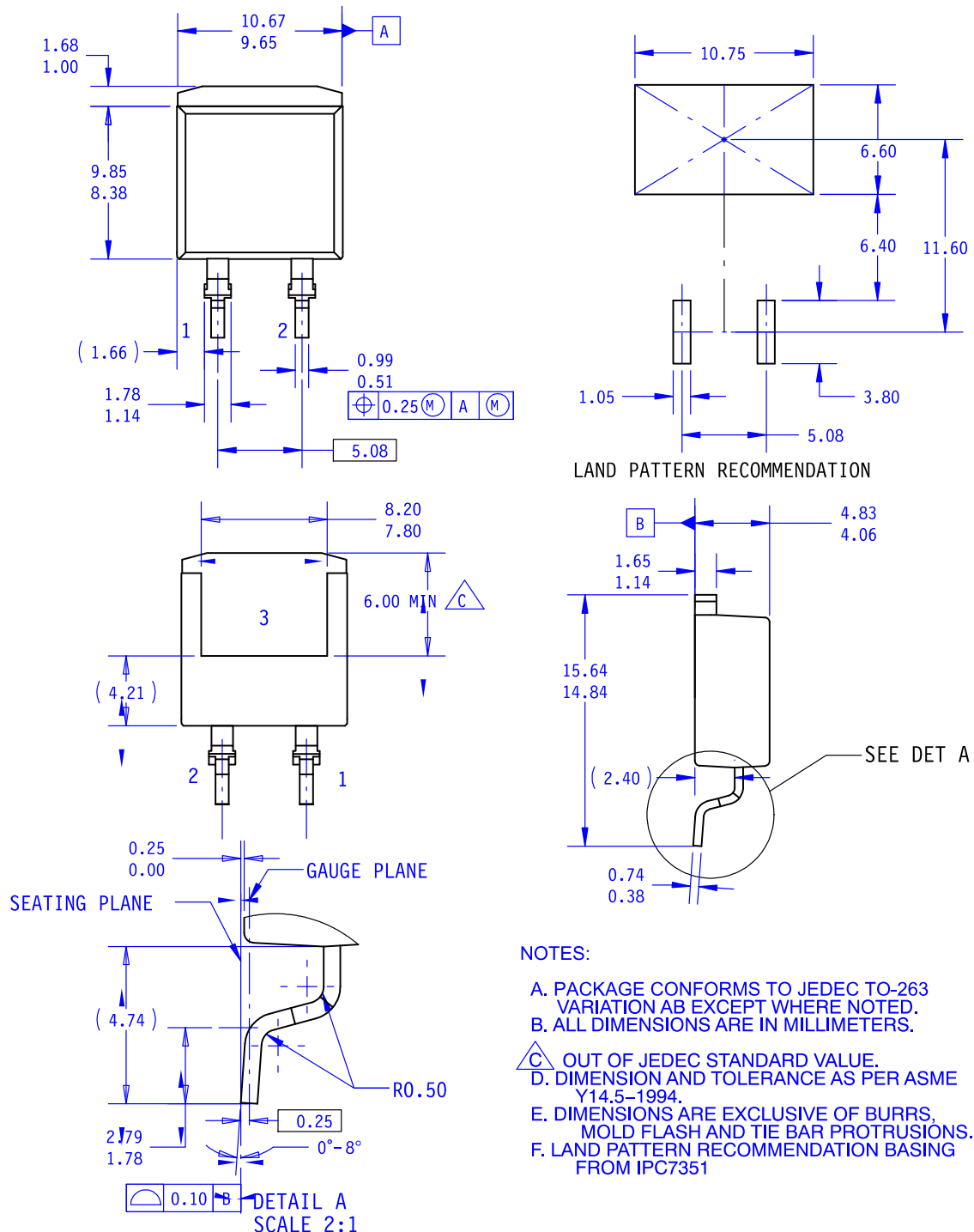


### D2PAK2 (TO-263 2 LD)

#### CASE 418AW

#### ISSUE O

DATE 30 SEP 2016



#### NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION AB EXCEPT WHERE NOTED.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. OUT OF JEDEC STANDARD VALUE.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- F. LAND PATTERN RECOMMENDATION BASING FROM IPC7351

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DESCRIPTION:	D2PAK2 (TO-263 2 LD)	PAGE 1 OF 1

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